

GHz Noise Suppression Chip Ferrite Bead BLM21HE□□□SH1□ Murata Standard Reference Specification [AEC-Q200]

1. Scope

This reference specification applies to GHz Noise Suppression Chip Ferrite Bead BLM21HE□□□SH1□ series for automotive electronics based on AEC-Q200.

2. Part Numbering

(Ex.)

BL	M	21	HE	601	S	H	1	L
Product ID	Type	Dimension (L × W)	Application and characteristic	Impedance	Performance	Category (H: for automotive electronics)	Number of line	Packaging L: taping *B: bulk

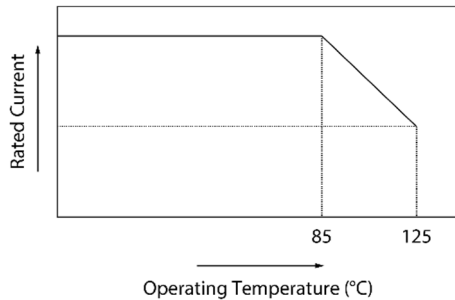
*B: Bulk packing is also available.

3. Part Number and Rating

Operating temperature range	-55°C to +125°C
Storage temperature range	-55°C to +125°C

Customer Part number	Murata Part number	Impedance (Ω) at 100 MHz	Impedance (Ω) at 1 GHz	Rated current* (mA)		DC resistance (Ω max.)		ESD rank
				Ambient temperature 85°C	Ambient temperature 125°C	Initial value	Value after testing	
	BLM21HE601SH1L	600±25%	450±40%	2300	1500	0.055	0.075	5A
	BLM21HE122SH1L	1200±25%	450±40%	1600	1100	0.11	0.14	5A
	BLM21HE472SH1L	4700±25%	750±40%	850	600	0.40	0.50	5A
	BLM21HE802SH1L	8000±25%	850±40%	650	500	0.70	0.90	5A

* As shown in the diagram below, derating is applied to the rated current based on the operating temperature

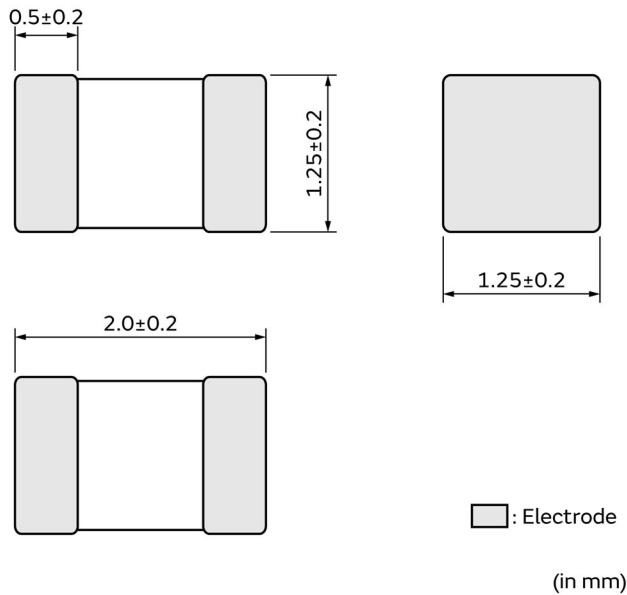


ESD Rank	Maximum Withstand Voltage
5A	8000 V (DC) to < 12,000 V (AD)

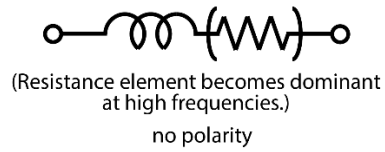
4. Testing Conditions

Unless otherwise specified	Temperature: ordinary temperature (15°C to 35°C) Humidity: ordinary humidity [25% to 85% (RH)]
In case of doubt	Temperature: 20°C±2°C Humidity: 60% to 70% (RH) Atmospheric pressure: 86 kPa to 106 kPa

5. Appearance and Dimensions



■ Equivalent Circuit



Unit mass (typical value): 0.0098 g

6. Marking

No marking.

7. Electrical Performance

No.	Item	Specification	Test method
7.1	Impedance	Meet chapter 3 ratings.	Measuring equipment: Keysight 4291A or the equivalent Measuring frequency: 100 MHz, 1 GHz Measuring fixture: Keysight 16197A or the equivalent
7.2	DC resistance	Meet chapter 3 ratings.	Measuring equipment: digital multimeter except resistance of the substrate and wire.

8. Q200 Requirement

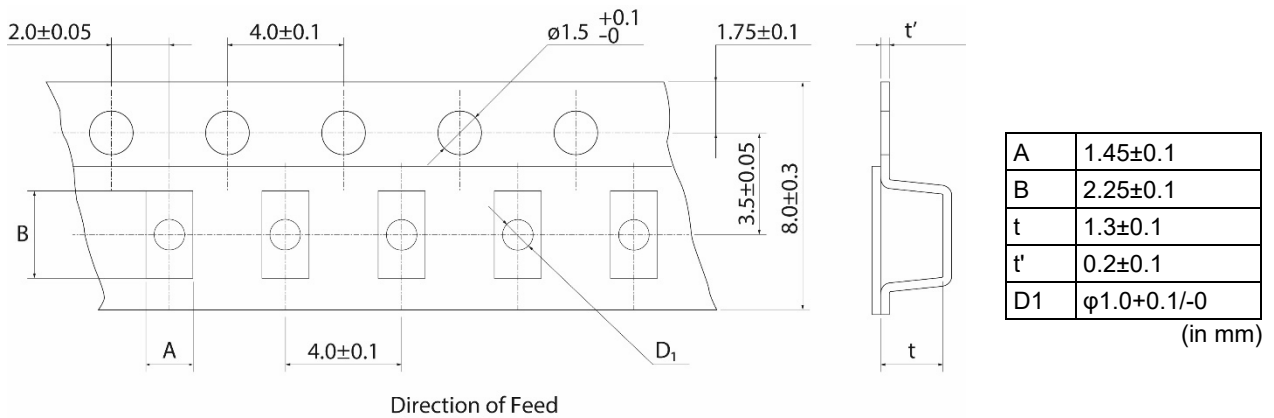
Performance(based on Table 13 for FILTER EMI SUPPRESSORS/FILTERS)
AEC-Q200 Rev.D issued June 1, 2010

AEC-Q200			Murata Specification / Deviation
No.	Stress	Test Method	
3	High temperature exposure	1000 h at 125°C Set for 24 h at room condition, then measured.	Appearance: No damage Impedance change rate: within ±50% DC resistance: Meet chapter 3, "Part Number and Rating".
4	Temperature cycling	1000 cycles -55°C to +125°C Set for 24 h at room condition, then measured.	Appearance: No damage Impedance change rate: within ±50% DC resistance: Meet chapter 3, "Part Number and Rating".
5	Destructive physical analysis	Per EIA469 No electrical tests	No defects
7	Biased humidity	1000 h at 85°C, 85% (RH). Apply max rated voltage and rated current. Set for 24 h at room condition, then measured.	Apply max rated current. Appearance: No damage Impedance change rate: within ±50% DC resistance: Meet chapter 3, "Part Number and Rating".
8	Operational life	Apply 125°C 1000 h Set for 24 h at room condition, then measured.	Applying current: Rated current at test temperature Appearance: No damage Impedance change rate: within ±50% DC resistance: Meet chapter 3, "Part Number and Rating".
9	External visual	Visual inspection	No abnormalities
10	Physical dimension	Meet chapter 5, "Appearance and Dimensions".	No defects

AEC-Q200			Murata Specification / Deviation
No.	Stress	Test Method	
12	Resistance to solvents	Per MIL-STD-202 Method 215	Not applicable
13	Mechanical shock	Per MIL-STD-202 Method 213 Condition F: 1500 g's/0.5 ms/half sine	Appearance: No damage Impedance change rate: within $\pm 30\%$ DC resistance: Meet chapter 3, "Part Number and Rating".
14	Vibration	5 g's for 20 min, 12 cycles each of 3 orientations Test from 10 Hz to 2000 Hz	Appearance: No damage Impedance change rate: within $\pm 30\%$
15	Resistance to Soldering Heat	No-heating Solder temperature $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ Immersion time 10 s	Appearance: No damage Impedance change rate: within $\pm 50\%$ DC resistance: Meet chapter 3, "Part Number and Rating". <u>Deviation for AEC-Q200</u> Pre-heating: $150^{\circ}\text{C}/60\text{s}$
17	ESD	Per AEC-Q200-002	ESD Rank: Refer to chapter 3, "Part Number and Rating". Appearance: No damage Impedance change rate: within $\pm 30\%$ DC resistance: Meet chapter 3, "Part Number and Rating".
18	Solderability	Per J-STD-002	95% or more of the outer electrode shall be covered with new solder seamlessly. <u>Deviation for AEC-Q200</u> Method b: Not applicable Pre-heating: $150^{\circ}\text{C}/60\text{s}$
19	Electrical Characterization	Measured: impedance	No defects
20	Flammability	Per UL-94	Not applicable
21	Board Flex	Epoxy-PCB (1.6 mm) Deflection 2 mm (min.) 60 s minimum holding time	Appearance: No damage Impedance change rate: within $\pm 30\%$
22	Terminal Strength	Per AEC-Q200-006 A force of 17.7 N for 60 s	Appearance: No damage
30	Electrical transient conduction	Per ISO-7637-2	Not applicable

9. Specification of Packaging

9.1 Appearance and dimensions of tape (8 mm width/plastic tape)



* The dimensions of the cavity are measured at its bottom.

9.2 Taping specifications

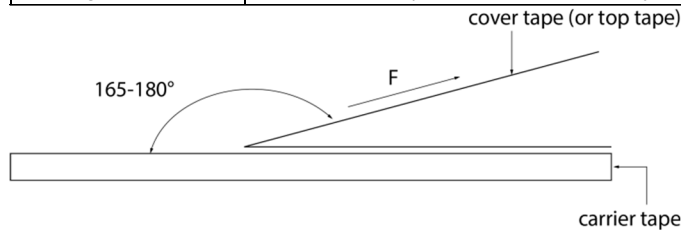
Packing quantity (Standard quantity)	3000 pcs/reel
Packing method	The products are placed in cavities of a carrier tape and sealed by a cover tape (top tape and bottom tape when the cavities of the carrier tape are punched type).
Feed hole position	The feed holes on the carrier tape are on the right side when the cover tape (top tape when the cavities of the carrier tape are punched type) is pulled toward the user.
Joint	The carrier tape and cover tape (top tape when the cavities of the carrier tape are punched type) are seamless.
Number of missing products	Number of missing products within 0.025% of the number per reel or 1 pc., whichever is greater, and are not continuous. The specified quantity per reel is kept.

9.3 Break down force of tape

Cover tape (or top tape)	5 N min.
Bottom tape (only when the cavities of the carrier tape are punched type)	5 N min.

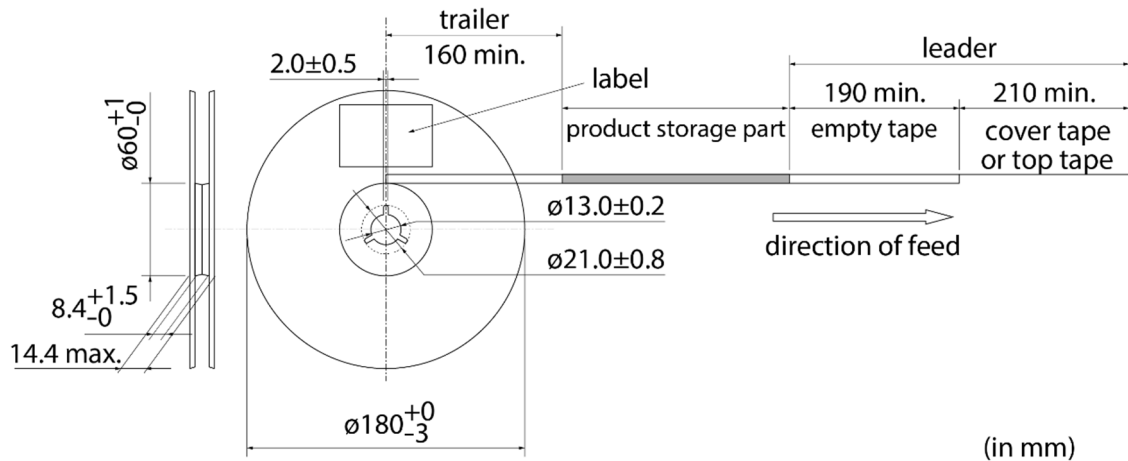
9.4 Peeling off force of tape

Speed of peeling off	300 mm/min
Peeling off force	0.1 N to 0.7 N (The lower limit is for typical value.)



9.5 Dimensions of leader section, trailer section and reel

A vacant section is provided in the leader (start) section and trailer (end) section of the tape for the product. The leader section is further provided with an area consisting only of the cover tape (or top tape). (See the diagram below.)



9.6 Marking for reel

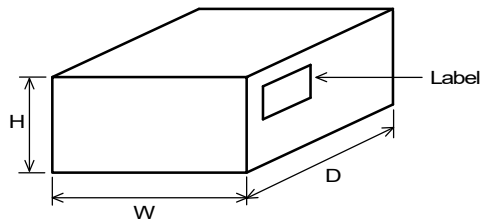
Customer part number, Murata part number, inspection number (*1), RoHS marking (*2), quantity, etc.

*1 Expression of inspection No.: $\frac{\square\square}{(1)}$ $\frac{\circ\circ\circ\circ}{(2)}$ $\frac{\diamond\diamond\diamond}{(3)}$	(1) Factory code (2) Date First digit: year/last digit of year Second digit: month/Jan. to Sep. → 1 to 9, Oct. to Dec. → O, N, D Third, Fourth digit: day (3) Serial No.
*2 Expression of RoHS marking: ROHS- $\frac{Y}{(1)}$ $\frac{(\Delta)}{(2)}$	(1) RoHS regulation conformity (2) Murata classification number

9.7 Marking on outer box (corrugated box)

Customer name, purchasing order number, customer part number, Murata part number, RoHS marking (*2), quantity, etc.

9.8 Specification of outer box



Dimensions of outer box (mm)			Standard reel quantity in outer box (reel)
W	D	H	
186	186	93	5
* Above outer box size is typical. It depends on a quantity of an order.			

10. Caution

10.1 Restricted applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

- | | |
|-----------------------------------|---|
| (1) Aircraft equipment | (6) Transportation equipment (trains, ships, etc.) |
| (2) Aerospace equipment | (7) Traffic signal equipment |
| (3) Undersea equipment | (8) Disaster/crime prevention equipment |
| (4) Power plant control equipment | (9) Data-processing equipment |
| (5) Medical equipment | (10) Applications of similar complexity and/or reliability requirements to the applications listed in the above |

10.2 Precautions on rating

Avoid using in exceeded the rated temperature range, rated voltage, or rated current.

Usage when the ratings are exceeded could lead to wire breakage, burning, or other serious fault.

10.3 Inrush current

If an inrush current (or pulse current or rush current) that significantly exceeds the rated current is applied to the product, overheating could occur, resulting in wire breakage, burning, or other serious fault.

10.4 Fail-safe

Be sure to provide an appropriate fail-safe function on your product to prevent a second damage that may be caused by the abnormal function or the failure of our product.

10.5 Corrosive gas

Please refrain from use since contact with environments with corrosive gases (sulfur gas [hydrogen sulfide, sulfur dioxide, etc.], chlorine, ammonia, etc.) or oils (cutting oil, silicone oil, etc.) that have come into contact with the previously stated corrosive gas environment will result in deterioration of product quality or an open from deterioration due to corrosion of product electrode, etc. We will not bear any responsibility for use under these environments.

11. Precautions for Use

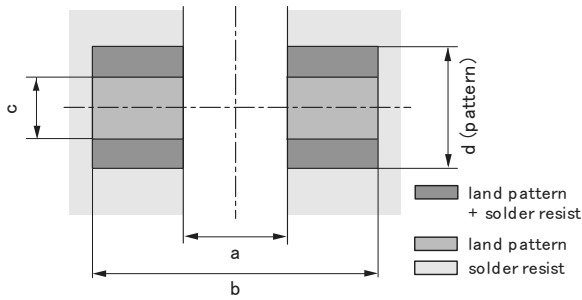
This product is designed to be mounted by soldering. If you want to use other mounting method, for example, using a conductive adhesive, please consult us beforehand.

Also, if repeatedly subjected to temperature cycles or other thermal stress, due to the difference in the coefficient of thermal expansion with the mounting substrate, the solder (solder fillet part) in the mounting part may crack.

The occurrence of cracks due to thermal stress is affected by the size of the land where mounted, the solder volume, and the heat dissipation of the mounting substrate. Carefully design it when a large change in ambient temperature is assumed.

11.1 Land dimensions

The following diagram shows the recommended land dimensions for flow and reflow soldering:



	a	b	c	Pattern thickness and dimension d	
				35 μm	70 μm
Flow	1.1	3.5	0.95	12.0	6.0
Reflow	1.2	2.4	1.25	12.0	6.0

If heat generation from patterns is large, please pay attention since the joint of products with substrates may deteriorate.

(in mm)

11.2 Flux and solder used

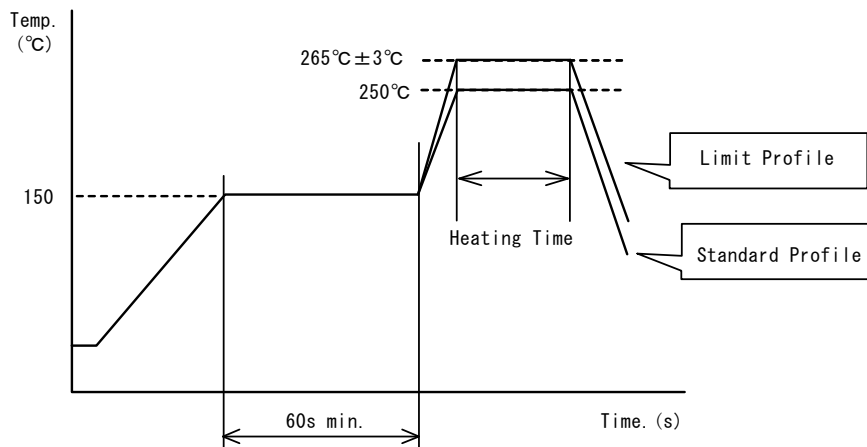
Flux	<ul style="list-style-type: none"> • Use a rosin-based flux. • Do not use a highly acidic flux with a halide content exceeding 0.2(wt)% (chlorine conversion value). • Do not use a water-soluble flux.
Solder	<ul style="list-style-type: none"> • Use Sn-3.0Ag-0.5Cu solder. • Standard thickness of solder paste: 100 μm to 200 μm

If you want to use a flux other than the above, please consult our technical department.

11.3 Soldering conditions (flow, reflow)

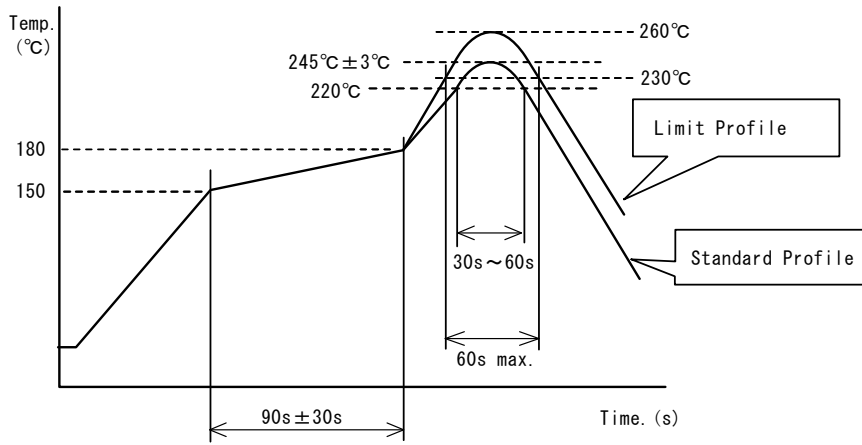
- Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 100°C max.
Cooling into solvent after soldering also should be in such a way that the temperature difference is limited to 100°C max.
- Insufficient pre-heating may cause cracks on the product, resulting in the deterioration of product quality.
- Standard soldering profile and the limit soldering profile is as follows.
The excessive limit soldering conditions may cause leaching of the electrode and/or resulting in the deterioration of product quality.

(1) Flow



	Standard profile	Limit profile
Pre-heating	150°C/60 s min.	150°C/60 s min.
Heating	250°C/4 s to 6 s	265°C±3°C/5 s
Number of flow cycles	2 times	2 times

(2) Reflow



	Standard profile	Limit profile
Pre-heating	150°C to 180°C/90 s±30 s	150°C to 180°C/90 s±30 s
Heating	Above 220°C/30 s to 60 s	Above 230°C/60 s max.
Peak temperature	245°C±3°C	260°C/10 s
Number of reflow cycles	2 times	2 times

11.4 Reworking with soldering iron

The following requirements must be met to rework a soldered product using a soldering iron.

Item	Requirement
Pre-heating	150°C/approx. 1 min
Tip temperature of soldering iron	350°C max.
Power consumption of soldering iron	60 W max.
Tip diameter of soldering iron	ø3 mm max.
Soldering time	3 s (+1 s, -0 s)
Number of reworking operations	2 times max.
* Avoid a direct contact of the tip of the soldering iron with the product. Such a direction contact may cause cracks in the ceramic body due to thermal shock.	

11.5 Solder volume

Solder shall be used not to increase the volume too much.

An increased solder volume increases mechanical stress on the product. Exceeding solder volume may cause the failure of mechanical or electrical performance.

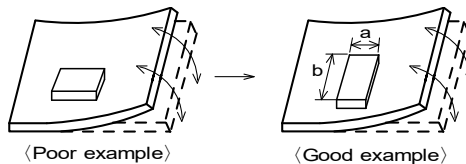
11.6 Product's location

The following shall be considered when designing and laying out PCBs.

(1) PCB shall be designed so that products are not subject to mechanical stress due to warping the board.

[Products direction]

Products shall be located in the sideways direction (length: $a < b$) to the mechanical stress.

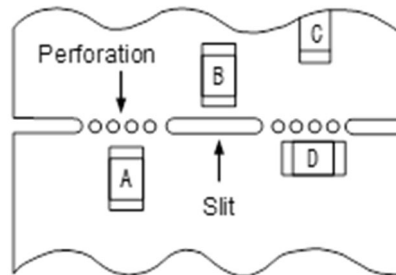


(2) Components location on PCB separation

It is effective to implement the following measures, to reduce stress in separating the board.

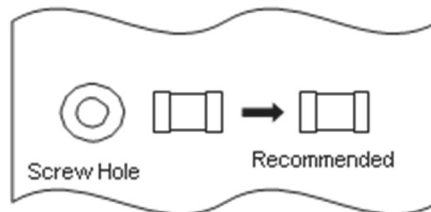
It is best to implement all of the following three measures; however, implement as many measures as possible to reduce stress.

Contents of measures	Stress level
(1) Turn the mounting direction of the component parallel to the board separation surface.	$A > D^{*1}$
(2) Add slits in the board separation part.	$A > B$
(3) Keep the mounting position of the component away from the board separation surface.	$A > C$
*1 $A > D$ is valid when stress is added vertically to the perforation as with hand separation. If a cutting disc is used, stress will be diagonal to the PCB, therefore $A > D$ is invalid.	

**(3) Mounting components near screw holes**

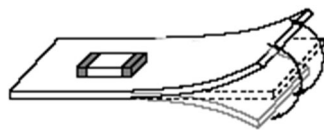
When a component is mounted near a screw hole, it may be affected by the board deflection that occurs during the tightening of the screw.

Mount the component in a position as far away from the screw holes as possible.

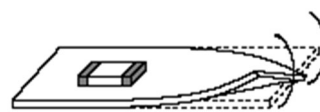
**11.7 Handling of substrate**

After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate.

Excessive mechanical stress may cause cracking in the product.



Bending



Twisting

11.8 Cleaning

Excessive ultrasonic oscillation during cleaning can cause the PCBs to resonate, resulting in cracked chips or broken solder joints. Before starting your production process, test your cleaning equipment / process to insure it does not degrade this product.